

- 1 1. A method comprising:
 - 2 positioning a wafer between a pair of rotating
 - 3 brushes; and
 - 4 providing a cleaning solution through at least
 - 5 one of said brushes.
- 1 2. The method of claim 1 including providing a
- 2 cleaning solution through the center of each of said
- 3 brushes.
- 1 3. The method of claim 1 wherein providing a
- 2 cleaning solution includes providing a solution of
- 3 deionized water and a cleaning chemical.
- 1 4. The method of claim 1 including spraying a
- 2 solution at the interface between said rotating brushes and
- 3 said wafer.
- 1 5. The method of claim 4 including using a spray bar
- 2 to spray the solution.
- 1 6. The method of claim 5 including spraying the
- 2 deionized water at the interface between the brushes and
- 3 wafers.

1 7. The method of claim 1 including providing the
2 cleaning solution to both of said brushes.

1 8. The method of claim 1 including cleaning wafers
2 after chemical mechanical polishing.

1 9. An apparatus comprising:
2 a pair of rotatable brushes to receive a wafer
3 between said brushes; and
4 a cleaning solution dispenser to dispense
5 cleaning solution from the interior of said brushes and to
6 flow outwardly through the brushes to the brush wafer
7 interface.

1 10. The apparatus of claim 9 including spray bars to
2 spray liquid at the brush wafer interface.

1 11. The apparatus of claim 10 wherein said spray bars
2 are coupled to a source of deionized water.

1 12. The apparatus of claim 9 including a reservoir to
2 supply a source of cleaning solution.

1 13. The apparatus of claim 12 including a mixer to
2 mix deionized water and a cleaning chemical to form the
3 cleaning solution.

1 14. The apparatus of claim 9 including a pipe that
2 provides a cleaning solution to the center of each of said
3 brushes and ejects said cleaning solution radially
4 outwardly through said brushes.

1 15. An apparatus for cleaning semiconductor wafers
2 after chemical mechanical polishing comprising:
3 a pair of counter-rotating brushes to receive a
4 wafer to be cleaned between said brushes;
5 a pair of spray bars to spray deionized water at
6 the brush wafer interface; and
7 a cleaning solution dispenser to dispense
8 cleaning solution from the center of each of said brushes
9 to flow outwardly through the brushes to the brush wafer
10 interface.

1 16. The apparatus of claim 15 including a mixer to
2 mix deionized water and a cleaning chemical to form a
3 cleaning solution.

1 17. The apparatus of claim 15 including a pipe that
2 extends through each of said brushes to dispense the
3 cleaning solution from the center of said brushes.